



HI882

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HI882 is designed for using in output stage of 10 W audio amplifier, voltage regulator, DC-DC converter and relay driver.

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 10 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 40 V
BVCEO Collector to Emitter Voltage 30 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current (DC) 3 A
IC Collector Current (Pulse) 7 A
IB Base Current (DC) 600 mA

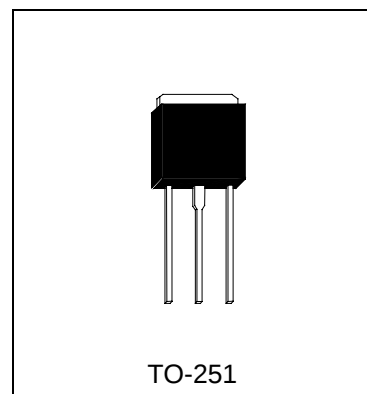
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	40	-	-	V	IC=100uA, IE=0
BVCEO	30	-	-	V	IC=1mA, IB=0
BVEBO	5	-	-	V	IE=10uA, IC=0
ICBO	-	-	1	uA	VCB=30V, IE=0
IEBO	-	-	1	uA	VEB=3V, IC=0
*VCE(sat)	-	0.3	0.5	V	IC=2A, IB=0.2A
*VBE(sat)	-	1	2	V	IC=2A, IB=0.2A
*hFE1	30	-	-		VCE=2V, IC=20mA
*hFE2	100	-	500		VCE=2V, IC=1A
fT	-	90	-	MHz	VCE=5V, IC=0.1A, f=100MHz
Cob	-	45	-	pF	VCB=10V, f=1MHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

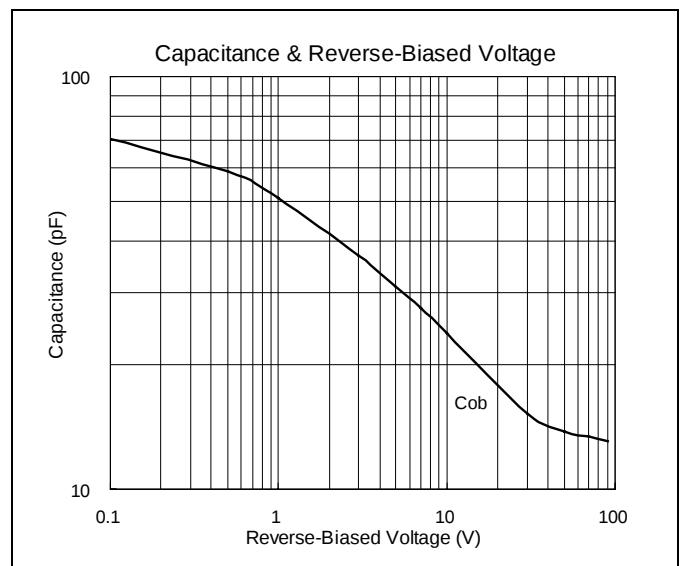
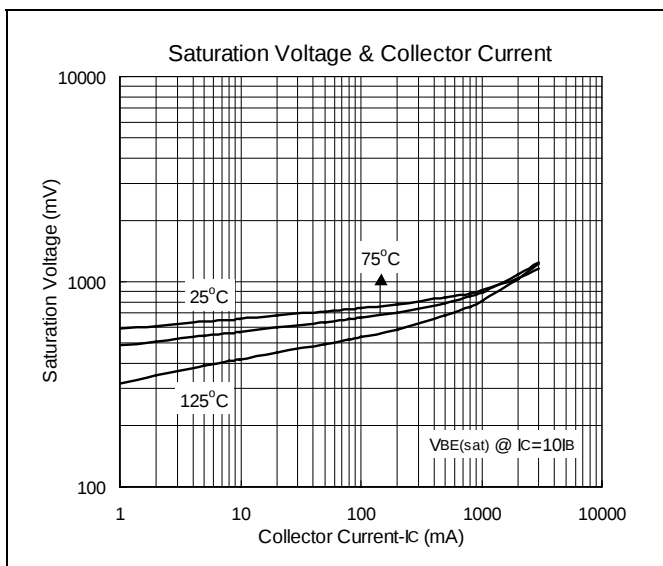
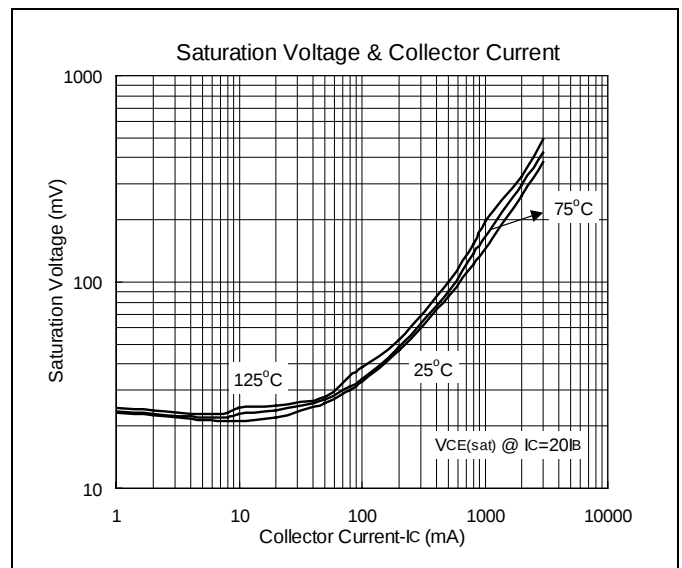
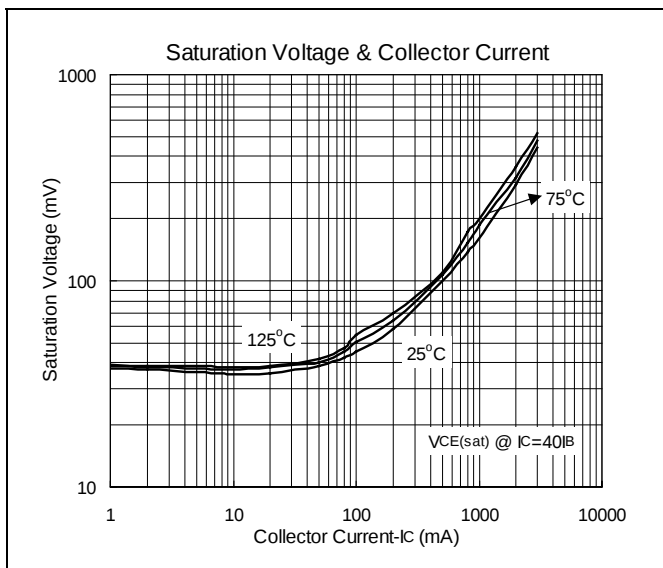
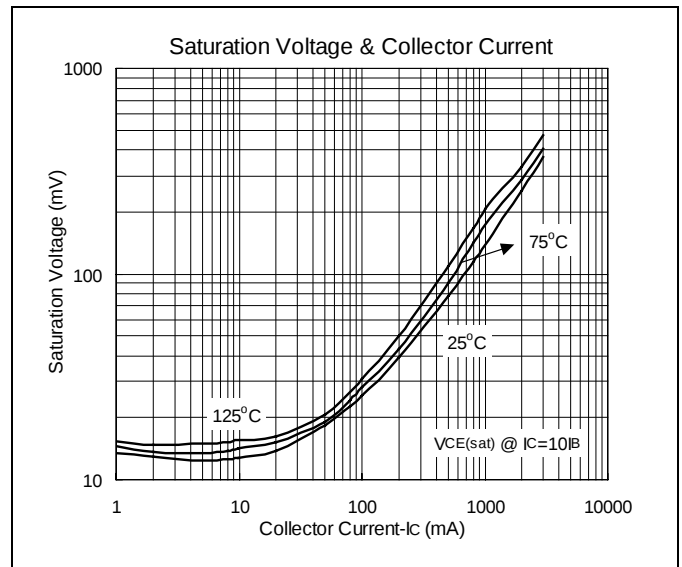
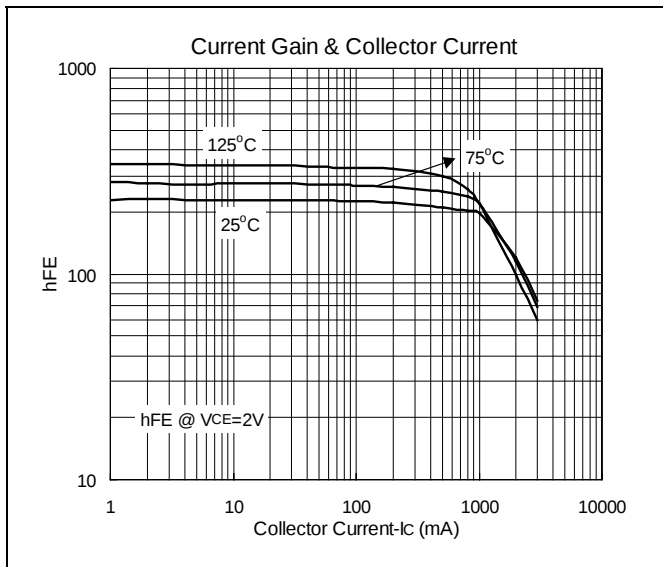
Classification Of hFE1

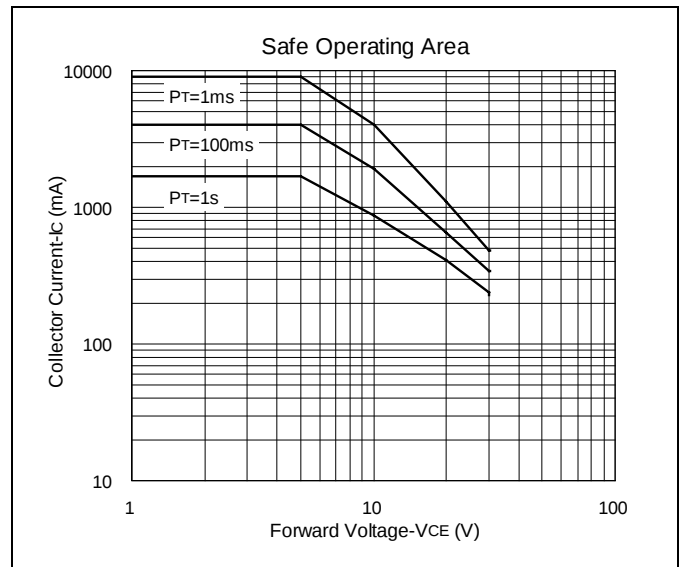
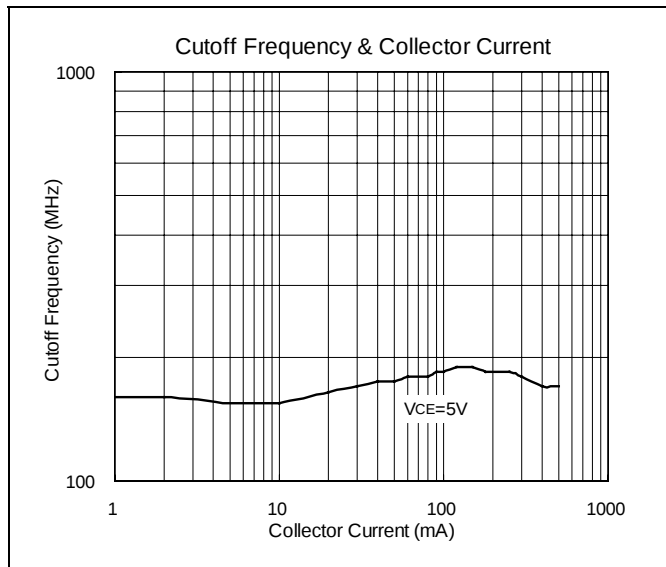
Rank	Q	P	E
Range	100-200	160-320	250-500





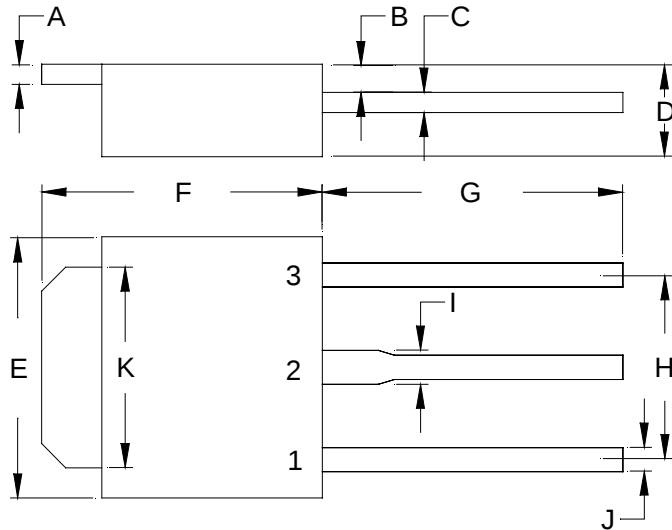
Characteristics Curve





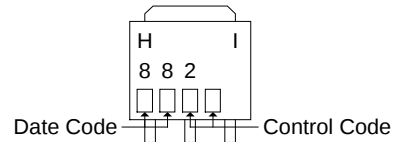


TO-251 Dimension



3-Lead TO-251 Plastic Package
HSMC Package Code: I

Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

Notes: 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel: 886-3-5983621~5 Fax: 886-3-5982931